















**ESD** 

TVS

MOS

LDO

Diode

Sensor

DC-DC

# **Product Specification**

Domestic Part Number	IRFB7437
Overseas Part Number	IRFB7437
▶ Equivalent Part Number	IRFB7437





#### **General Description**

- Advanced Trench MOS Technology
- Low Gate Charge
- Low Rds(ON)
- 100% EAS Guaranteed
- Green Device Available

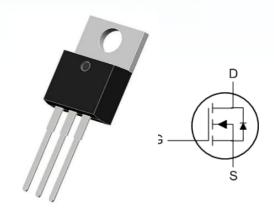
# **Applications**

- SMPS Synchronous Rectification
- DC/DC Converters
- Or-ing

## **Product Summary**

BVDSS	RDSON ID	
40V	$2.8 m\Omega$	170A

# **TO220 Pin Configuration**



# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage	40	V	
V <sub>G</sub> s	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	170	Α	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	142	А	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	340	А	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	320	mJ	
I <sub>AS</sub>	Avalanche Current	80	Α	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation⁴	178	W	
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	Ĵ	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
Reja	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
R <sub>θ</sub> JC	Thermal Resistance Junction-Case <sup>1</sup>		0.7	°C/W



#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0 $V$ , $I_D$ =250 $u$ A	40			V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}$ =10V , $I_D$ =20A		2.4	2.8	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	2.8	4	V
lpss	Drain Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	
IDSS	Drain-Source Leakage Current	$V_{DS}$ =32V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			5	uA
Igss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		53		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.9		Ω
Qg	Total Gate Charge			60		
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =20V , V <sub>GS</sub> =10V , I <sub>D</sub> =20A		14.7		nC
$Q_{gd}$	Gate-Drain Charge			13.9		
T <sub>d(on)</sub>	Turn-On Delay Time			11.4		
Tr	Rise Time	$V_{DD}$ =20V , $V_{GS}$ =10V , $R_{G}$ =3 $\Omega$ , $I_{D}$ =20A		41.6		
T <sub>d(off)</sub>	Turn-Off Delay Time			42.8		ns
T <sub>f</sub>	Fall Time			27.2		
Ciss	Input Capacitance			3739		
Coss	Output Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		1267		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			106		

#### **Diode Characteristics**

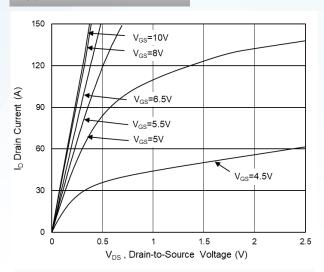
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			130	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =80A
- 4. The power dissipation is limited by 150°C junction temperature.
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.
- 6.Bonding wire limitation current is 85A.



# **Typical Characteristics**



#### **Fig.1 Typical Output Characteristics**

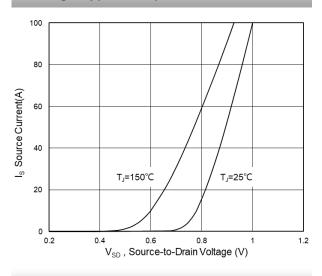


Fig.3 Source Drain Forward Characteristics

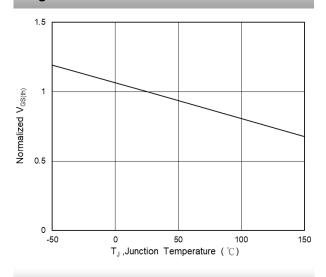


Fig.5 Normalized V<sub>GS(th)</sub> vs T<sub>J</sub>

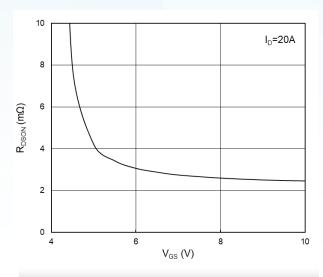


Fig.2 On-Resistance vs G-S Voltage

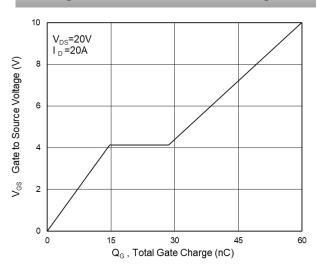


Fig.4 Gate-Charge Characteristics

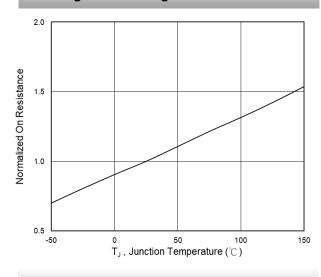
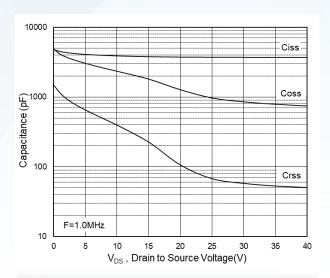


Fig.6 Normalized R<sub>DSON</sub> vs T<sub>J</sub>





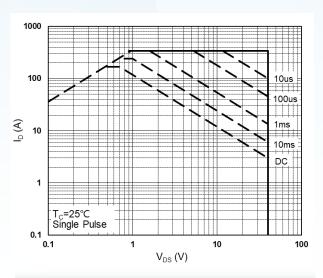


Fig.7 Capacitance

Fig.8 Safe Operating Area

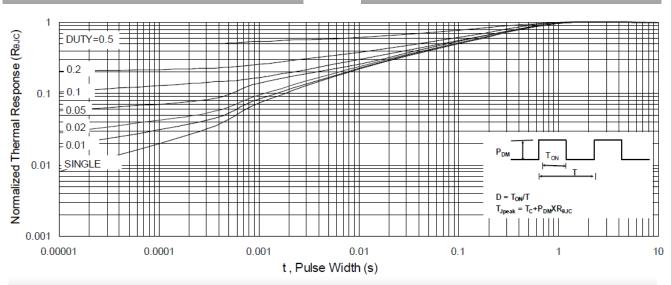
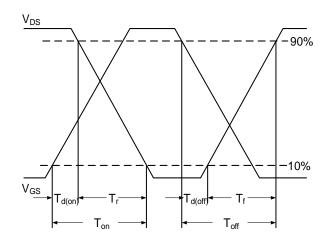


Fig.9 Normalized Maximum Transient Thermal Impedance



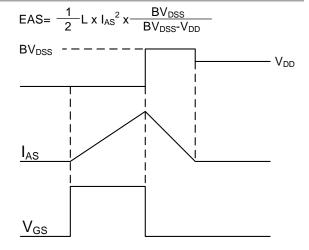


Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform



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